



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

*Handwritten:* #8/Response (NE) 2800

In re the Application of: Chakravarthi et al.

Docket No. TI-33161

Serial No. 10/020,813

Art Unit: 2813

Filed: 12/12/01

Examiner: Yennhu B. Huynh

*Handwritten:* 3/17/03  
Amth

Title: Fabrication of Ultra Shallow Junctions From a Solid Source With Fluorine Implantation

REPLY UNDER 37 CFR 1.116 – EXPEDITED PROCEDURE  
TECHNOLOGY CENTER 2800

March 5, 2003

Assistant Commissioner  
for Patents  
Washington, D. C. 20231

Dear Sir:

<b>MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)</b>			
I hereby certify that the above correspondence is being deposited			
with	the	U.S.	Postal Service on
	<u>3-5-03</u>		as First Class Mail in an
envelope addressed to: Assistant Commissioner for Patents,			
Washington, D.C.			
<u>Karen Vertz</u>		<u>3-5-03</u>	
Karen Vertz		Date	

In response to the Office Action, dated 1/14/03, in the above-identified patent application, please make the following amendments. They are respectfully submitted as a full and complete response to that Action. Charge any required fees to the deposit account of Texas Instruments Incorporated, Account No. 20-0668.

*Handwritten:* Do not enter  
4H  
3/20/03

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